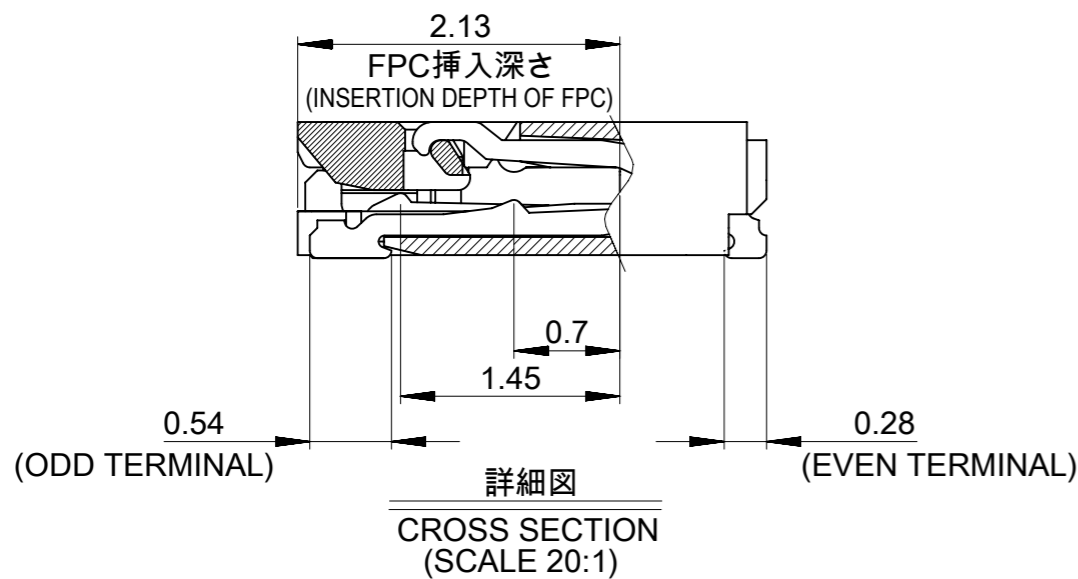


回路番号1
CIRCUIT NO.1



注記

NOTES:

1.材質

MATERIAL

ハウジング : LCP (液晶ポリマー)、ガラス充填、UL94V-0
HOUSING: LCP (LIQUID CRYSTAL POLYMER),
GLASS FILLED, UL94V-0

アクチュエータ : ナイロン、ガラス充填、UL94HB
ACTUATOR: NYLON (POLYAMIDE),
GLASS FILLED, UL94HB

ターミナル : 銅合金 (t=0.15)

TERMINAL: COPPER ALLOY (t=0.15)

金具 : 銅合金 (t=0.15)

NAIL: COPPER ALLOY (t=0.15)

2.めっき仕様

PLATING

ターミナル

TERMINAL

部分金めっき

SEPARATED GOLD PLATING

下地ニッケルめっき

UNDER PLATING: NICKEL PLATING

金具

NAIL

錫めっき

TIN PLATING

下地ニッケルめっき

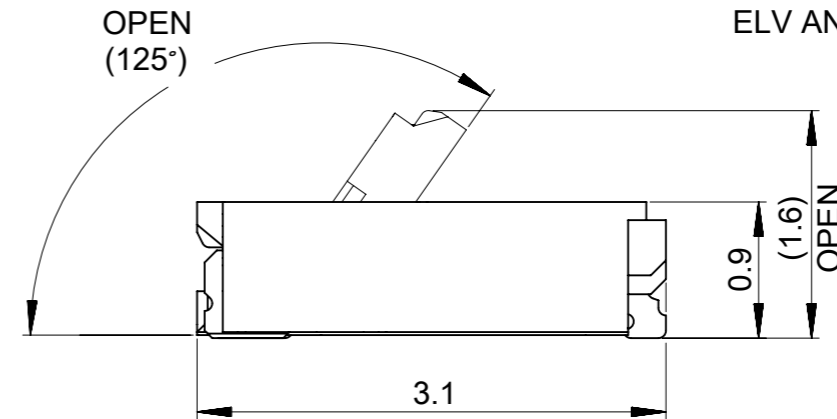
UNDER PLATING: NICKEL PLATING

3.平坦度は、0.1ミリ以下とする。

TAILS COPLANARITY TO BE 0.1 MAXIMUM.

4.ELV及びRoHS適合品

ELV AND RoHS COMPLIANT



0.067	10.75	9.0	9.6	12.0	501628-3391	33
重さ (g) WEIGHT(g)	D	C	B	A	EMBOSSED PACKAGE オーダー番号 ORDER No.	極数 CIRCUITS

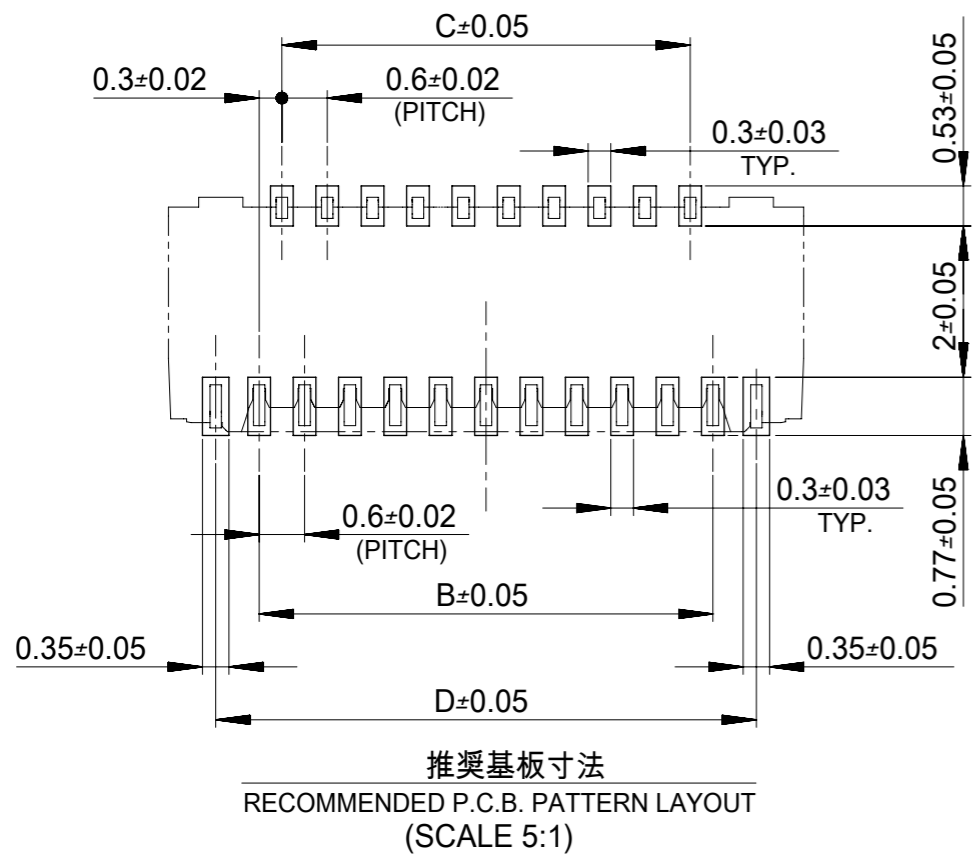
CONNECTOR SERIES No. 501628-**13

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

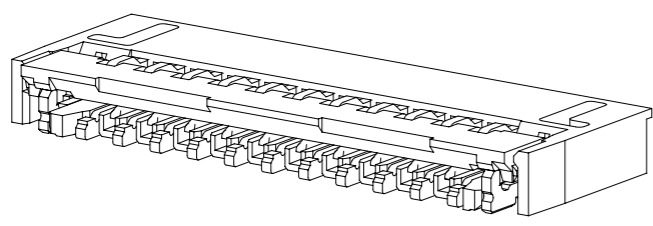
DIMENSION UNITS		SCALE		CURRENT REV DESC: OBSOLETE PART NO.			
mm		40:1		<p>molex</p> <p>0.3 FPC CONN. (H=0.9) HS'G ASSY BOTTOM CONTACT NICKEL BARRIER</p> <p>PRODUCT CUSTOMER DRAWING</p> <p>DOCUMENT NUMBER: SD-501628-001 DOC TYPE: PSD DOC PART: 001 REVISION: M1</p> <p>MATERIAL NUMBER: SEE TABLE CUSTOMER: GENERAL MARKET SHEET NUMBER: 1 OF 2</p>			
GENERAL TOLERANCES (UNLESS SPECIFIED)							
4 PLACES	±	MM	INCH				
3 PLACES	±						
2 PLACES	±						
1 PLACE	±			EC NO: 631031	DRWN: RPRABHUM	2019/12/24	
0 PLACES	±			CHK'D: GGA	2020/02/06		
ANGULAR TOL ± 1.0°				APPR: GGA	2020/02/06		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				THIRD ANGLE PROJECTION	DRAWING: A3-SIZE	SERIES: 501628	

GENERAL TOLERANCES (UNLESS SPECIFIED)

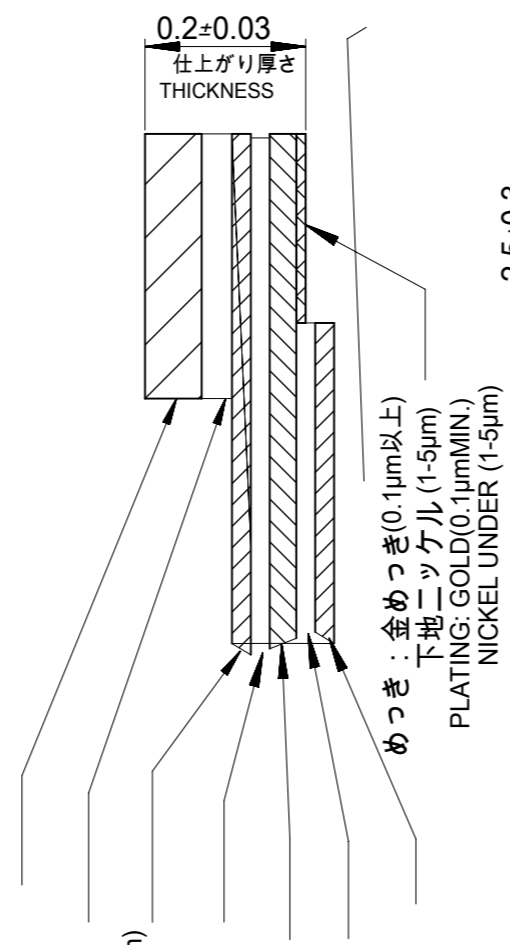
10 ^{UNDER}	±0.2
10 ^{OVER} 30 ^{UNDER}	±0.25
30 ^{OVER}	±0.3



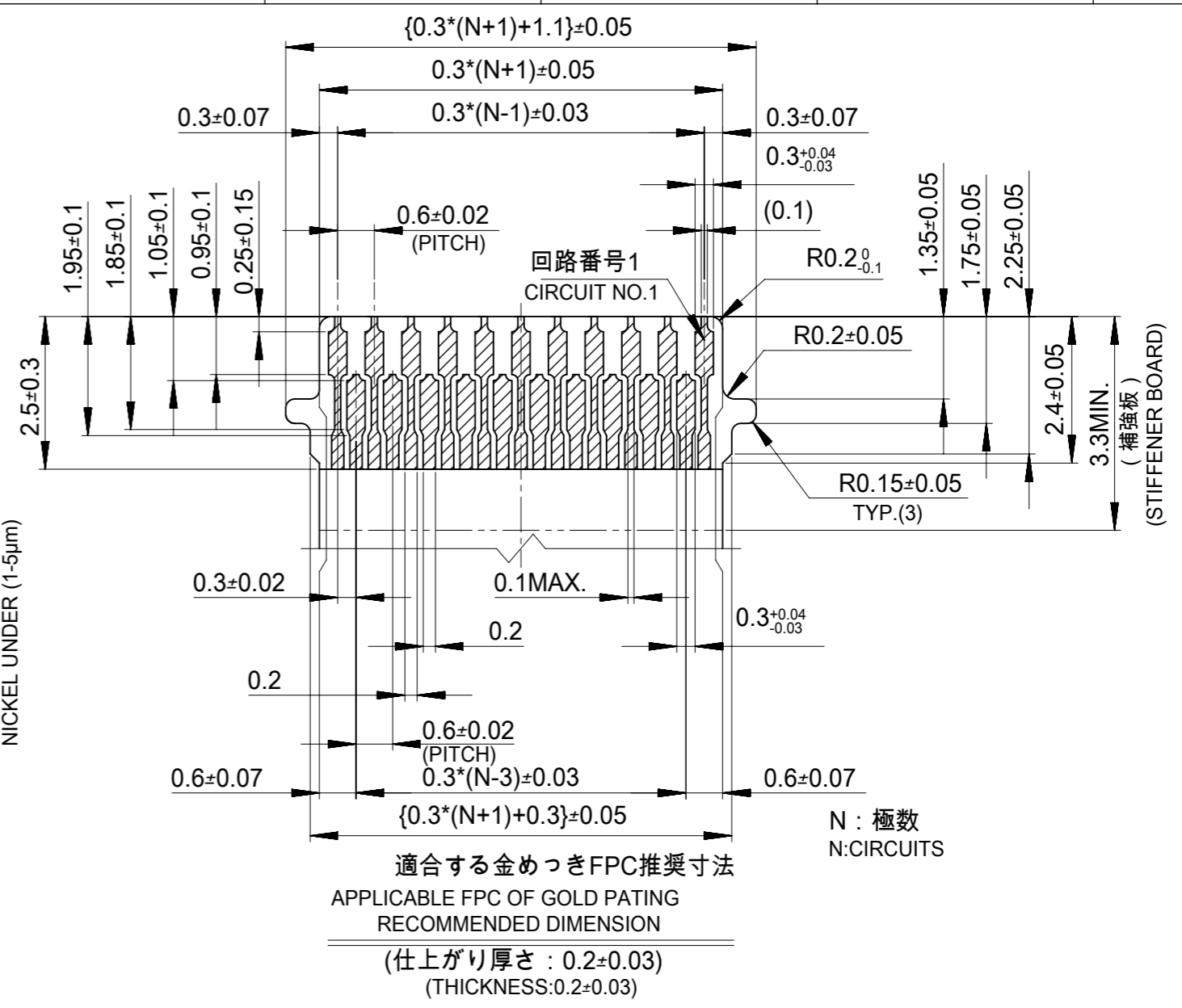
推奨基板寸法
RECOMMENDED P.C.B. PATTERN LAYOUT
(SCALE 5:1)



ISO VIEW (参考)



- FPC構成推奨仕様
STRUCTURE OF FPC
- 補強板: ポリイミド REINFORCE BOARD: POLYIMIDE
 - 熱硬化接着剤 THERMOSETTING ADHESIVE
 - ベースフィルム: ポリイミド (25 μ m) BASE FILM: POLYIMIDE (25 μ m)
 - 熱硬化接着剤 THERMOSETTING ADHESIVE
 - 導体部: 銅箔 (35 μ m) COPPER FOIL (35 μ m)
 - 熱硬化接着剤 THERMOSETTING ADHESIVE
 - カバーレイ: ポリイミド (25 μ m) COVER FILM: POLYIMIDE (25 μ m)



FPCについて:
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。

ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM: POLYIMIDE
BONDING AGENT: THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ASHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.

GENERAL TOLERANCES (UNLESS SPECIFIED)

10 ^{UNDER}	± 0.2
10 ^{OVER} 30 ^{UNDER}	± 0.25
30 ^{OVER}	± 0.3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DIMENSION UNITS: mm	SCALE: 40:1	CURRENT REV DESC: OBSOLETE PART NO.
GENERAL TOLERANCES (UNLESS SPECIFIED)		EC NO: 631031 DRWN: RPRABHUM 2019/12/24 CHK'D: GGA 2020/02/06 APPR: GGA 2020/02/06
4 PLACES	\pm	
3 PLACES	\pm	INITIAL REVISION: DRWN: HSHIMYAMA 2005/03/25 APPR: MSASAO 2005/03/25
2 PLACES	\pm	
1 PLACE	\pm	DOCUMENT NUMBER: SD-501628-001
0 PLACES	\pm	DOC TYPE: PSD
ANGULAR TOL: $\pm 1.0^\circ$		DOC PART: 001
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION	REVISION: M1
	DRAWING: A3-SIZE	SHEET NUMBER: 2 OF 2
	SERIES: 501628	
	MATERIAL NUMBER: SEE TABLE	
	CUSTOMER: GENERAL MARKET	

F

E

D

C

B

A

F

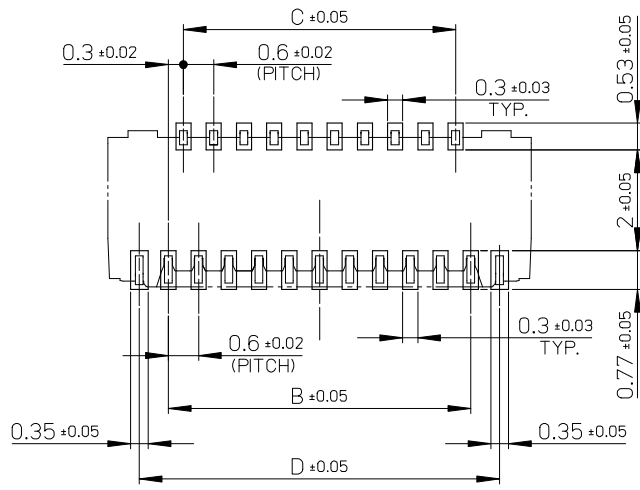
E

D

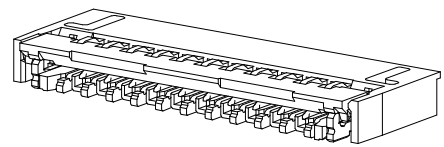
C

B

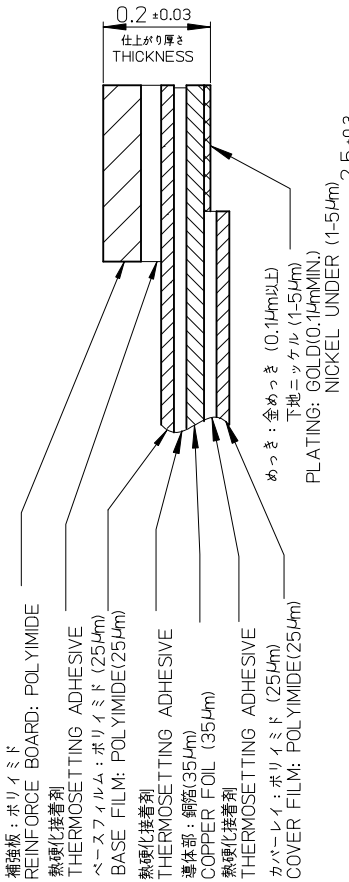
A



推奨基板寸法
RECOMMENDED P.C.B. PATTERN LAYOUT
(SCALE 5:1)

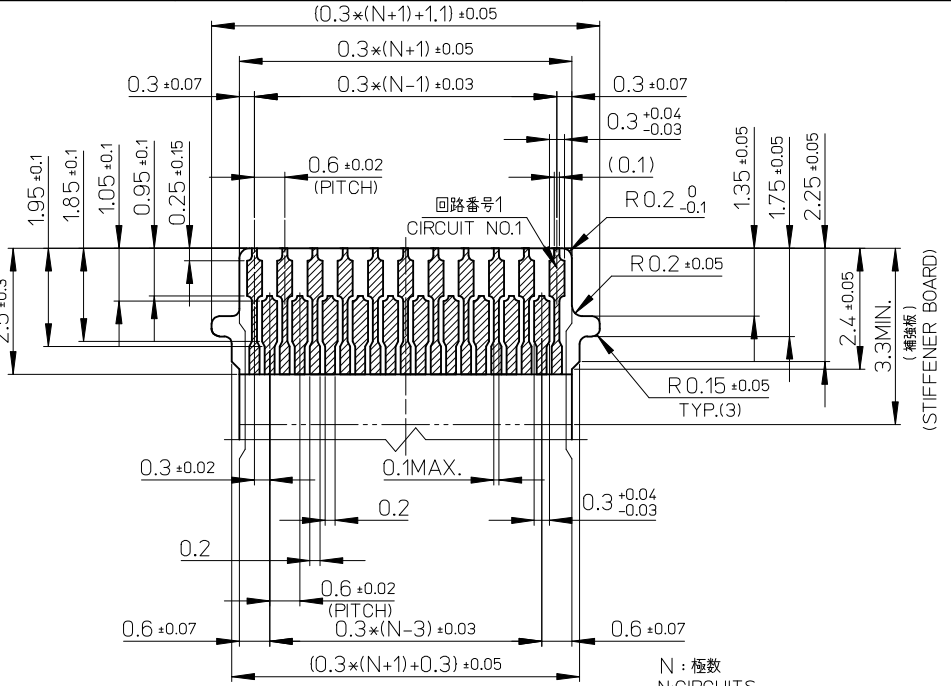


ISO VIEW (参考)



補強板: ポリイミド
REINFORCE BOARD: POLYIMIDE
熱硬化接着剤
THERMOSETTING ADHESIVE
ベースフィルム: ポリイミド (25μm)
BASE FILM: POLYIMIDE(25μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
導体部: 銅箔 (35μm)
COPPER FOIL (35μm)
熱硬化接着剤
THERMOSETTING ADHESIVE
カバーレイ: ポリイミド (25μm)
COVER FILM: POLYIMIDE(25μm)

FPC構成推奨仕様
STRUCTURE OF FPC

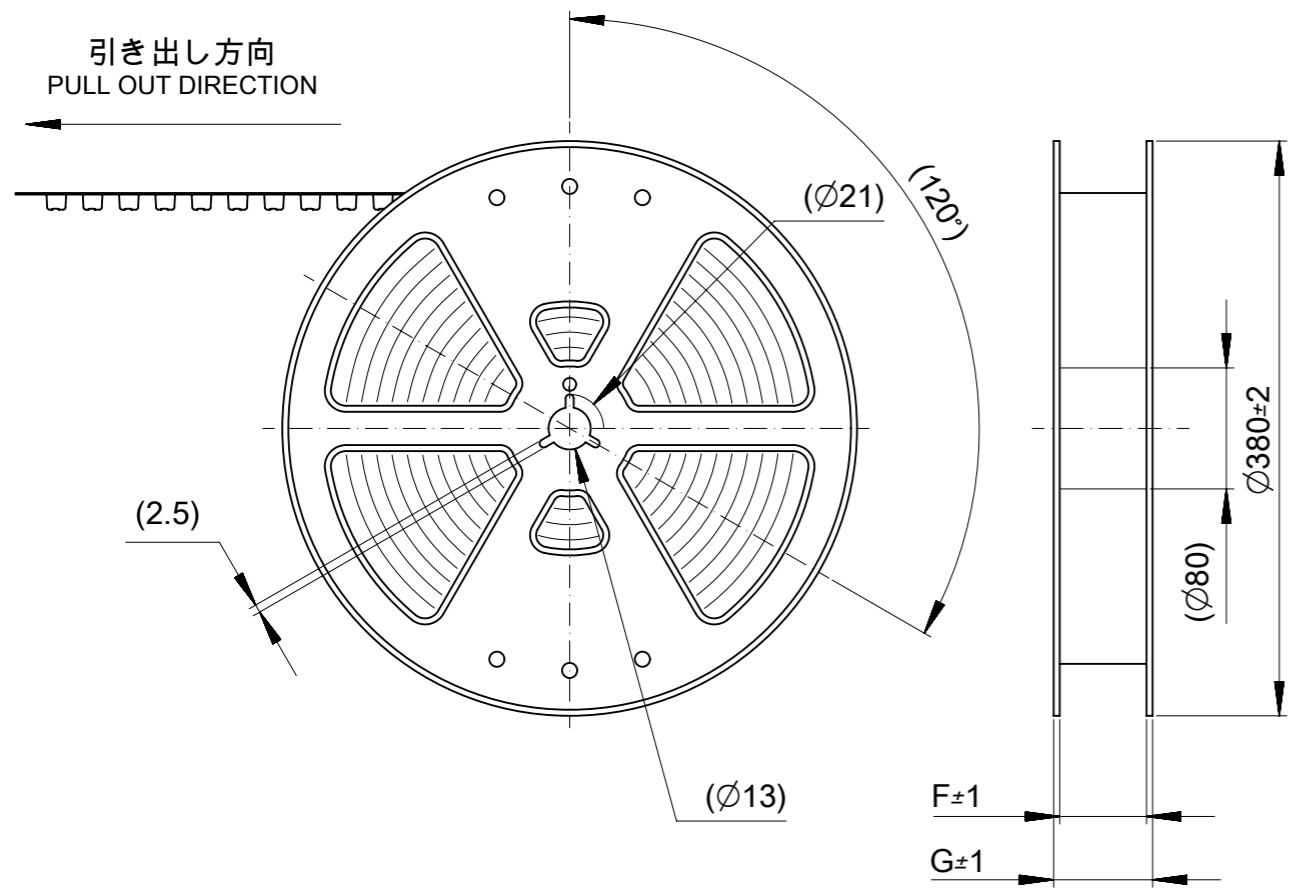


適合する金めっきFPC推奨寸法
APPLICABLE FPC OF GOLD PATING
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.2 ± 0.03)
(THICKNESS: 0.2 ± 0.03)

FPCについて:
抜き方向は、導体側から補強板側を推奨致します。
補強フィルム材質は、ポリイミドを推奨致します。
接着剤は熱硬化接着剤を推奨致します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、
染み出しが無い様、お願い致します。

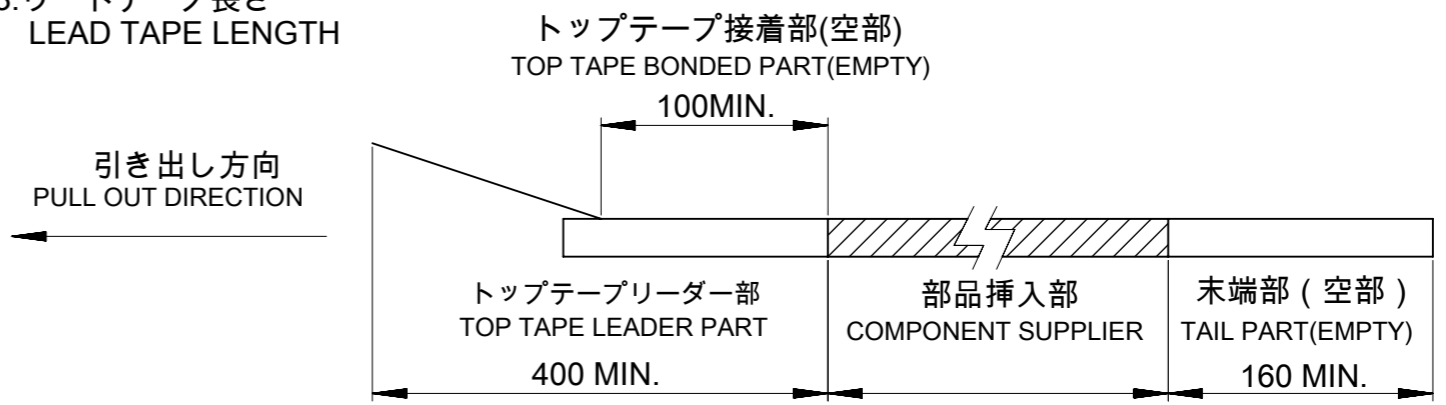
ABOUT FPC:
RECOMMENDED PUNCHER DIRECTION:
FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
RECOMMENDED MATERIAL:
STIFFENER FILM : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ASHESIVE ON THE CONTACT AREA BECAUSE THE EXTRA ADHESIVE MAY CAUSE THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2010-0068 DRWN: KUSATO 2009/07/30 CHKD: HSHIMOYAMA 2009/07/31 APPR: KMORIKAWA 2009/07/31	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 40:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	± 0.2	DRAWN BY HSHIMOYAMA	DATE 2005/03/25	TITLE 0.3 FPC CONN. (H=0.9) HS'G ASSY BOTTOM CONTACT NICKEL BARRIER			
		10 OVER 30 UNDER	± 0.25	CHECKED BY HHIRATA	DATE 2005/03/25	MOLEX INCORPORATED			
		30 OVER	± 0.3	APPROVED BY MSASAO	DATE 2005/03/25	DOCUMENT NO. SD-501628-001			
ANGULAR ± 1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE TABLE		SHEET NO. 2 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	

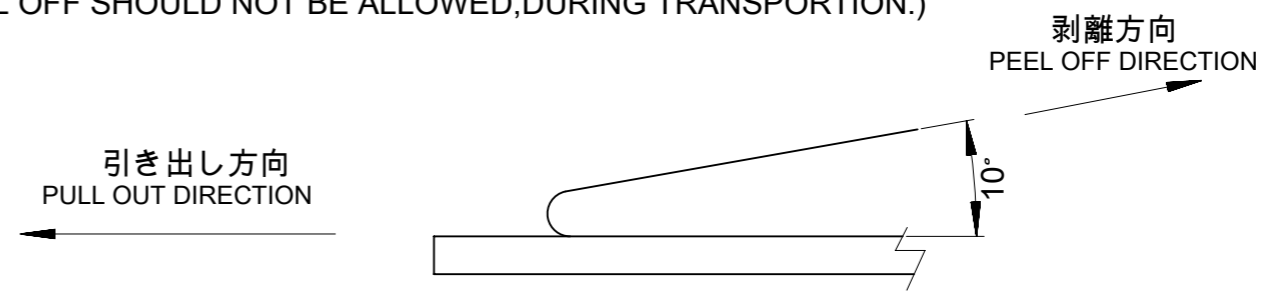


注記)
NOTES

1. 製品番号501628-**11の詳細寸法は、製品単体図面を参照下さい。
IN THE PACKAGE PART NUMBER 501628-**11 DETAIL DIMENSIONS, SEE SALES DRAWING FOR CONNECTOR.
2. 梱包数量：3000個/リール
NUMBER OF CONNECTORS：3000 PCS/REEL
3. リードテープ長さ
LEAD TAPE LENGTH



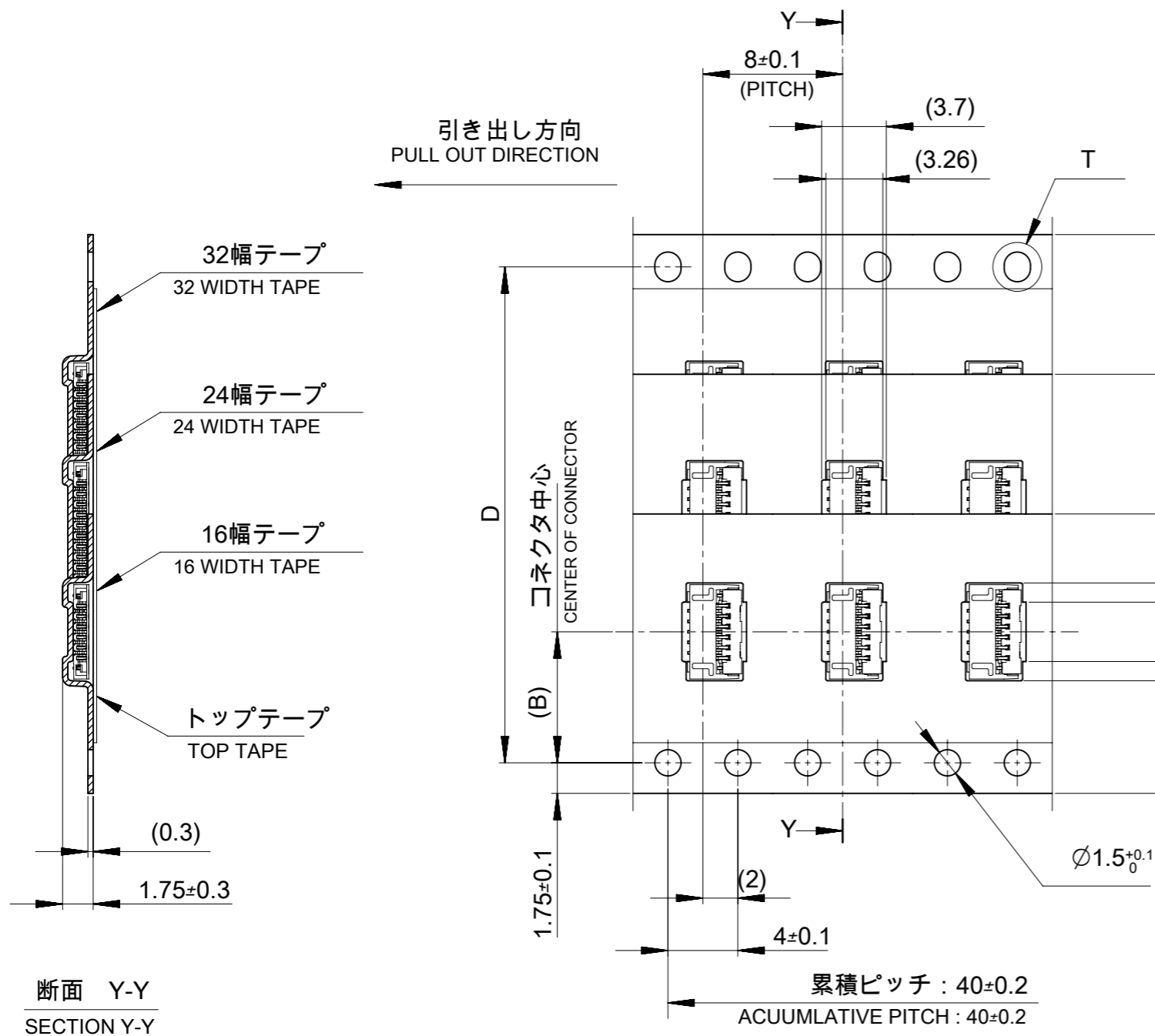
4. トップテープの剥離強度 (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE (PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
0.1-1.3N (10-130gf)
尚、本規格値は出荷時に適用。
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
(但し、輸送時に剥離が発生しないこと)
(PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTION.)



5. 材料
MATERIAL
キャリアテープ：ポリスチレン (PS)
CARRIER TAPE: POLYSTYRENE (PS)
トップテープ：PET、PE、PEF
TOP TAPE: PET, PE, PEF
リール：ポリスチレン
REEL: POLYSTYRENE

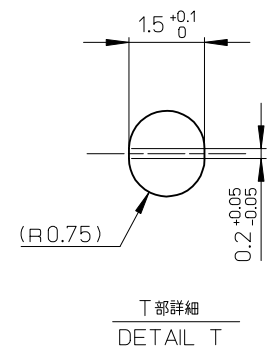
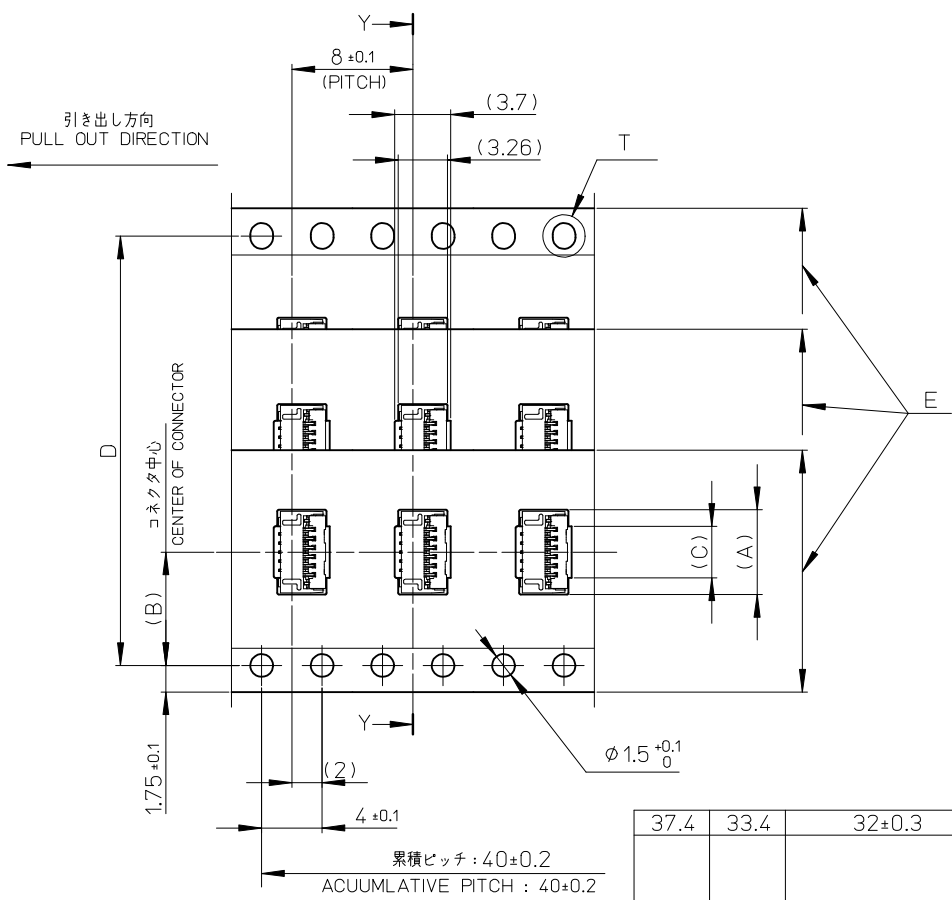
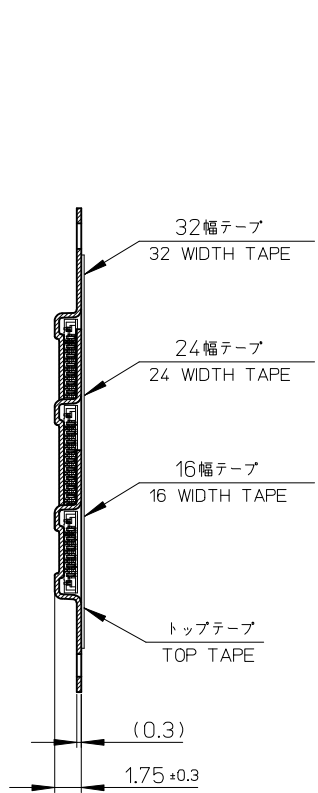
6. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC: OBSOLETE PART NO.		molex	
DIMENSION UNITS	SCALE				
mm	NTS			0.3 FPC CONN.(FOR 501628-**11) TAPING PACKAGE NICKEL BARRIER	
GENERAL TOLERANCES (UNLESS SPECIFIED)				PRODUCT CUSTOMER DRAWING	
	MM	INCH			
4 PLACES	±	±	EC NO: 631031	DOCUMENT NUMBER	
3 PLACES	±	±	DRWN: RPRABHUM 2019/12/24	SD-501628-003	DOC TYPE
2 PLACES	±	±	CHK'D: GGA 2020/02/06	PSD	DOC PART
1 PLACE	±	±	APPR: GGA 2020/02/06	001	REVISION
0 PLACES	±	±	INITIAL REVISION:	G1	
			DRWN: HSHIMOYAMA 2005/08/22		
			APPR: MSASAO 2005/08/22		
ANGULAR TOL	±	°			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	THIRD ANGLE PROJECTION		DRAWING	SERIES	MATERIAL NUMBER
	A3-SIZE		501628	CUSTOMER	SHEET NUMBER
	SEE TABLE		GENERAL MARKET	1 OF 2	



29.4	25.4	24±0.3	---	10.0	11.5	12.2	501628-3391	33
G	F	キャリアテープ幅 EMBOSSD TAPE WIDTH	D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		CURRENT REV DESC: OBSOLETE PART NO.		molex	
DIMENSION UNITS: mm		SCALE: NTS			
GENERAL TOLERANCES (UNLESS SPECIFIED)				0.3 FPC CONN.(FOR 501628 -**11) TAPING PACKAGE NICKEL BARRIER	
4 PLACES ±				EC NO: 631031	
3 PLACES ±				DRWN: RPRABHUM 2019/12/24	
2 PLACES ±				CHK'D: GGA 2020/02/06	
1 PLACE ±				APPR: GGA 2020/02/06	
0 PLACES ±				INITIAL REVISION:	
ANGULAR TOL ± °				DRWN: HSHIMOYAMA 2005/08/22	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				APPR: MSASAO 2005/08/22	
THIRD ANGLE PROJECTION		DRAWING		DOCUMENT NUMBER	
A3-SIZE		SERIES		DOC TYPE	
501628		MATERIAL NUMBER		DOC PART	
SEE TABLE		CUSTOMER		REVISION	
GENERAL MARKET		SHEET NUMBER		G1	
2 OF 2					



37.4	33.4	32±0.3	28.4	15.4	14.2	17.6	501628-5191	51	
29.4	25.4	24±0.3	---	13.6	11.5	15.8	501628-4591	45	
				11.8		14	501628-3991	39	
				11.2		13.4	501628-3791	37	
				10.6		12.8	501628-3591	35	
				10.0		12.2	501628-3391	33	
				9.4		11.6	501628-3191	31	
21.4	17.4	16±0.3	---	8.2	7.5	10.4	501628-2791	27	
				6.4		8.6	501628-2191	21	
				3.4		5.6	501628-1191	11	
G	F	E キャリアテープ幅 EMBOSSED TAPE WIDTH		D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUITS

REVISED EC NO: J2010-0068 DRW: KUSATO 2009/07/30 CHK: HSHIMUYAMA 2009/07/31 APP: KMORIKAWA 2009/07/31	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC		THIRD ANGLE PROJECTION	
		10 UNDER	± ---	DRAWN BY HSHIMUYAMA	DATE 2005/08/22	TITLE 0.3 FPC CONN.(FOR 501628 -**11) TAPING PACKAGE NICKEL BARRIER				
		10 OVER 30 UNDER	± ---	CHECKED BY HHRATA	DATE 2005/08/22	MOLEX INCORPORATED				
		30 OVER	± ---	APPROVED BY MSASAO	DATE 2005/08/22	MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-501628-003	SHEET NO. 2 OF 2	
ANGULAR ± --- °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						